

Maximum Ratings @T_A = +25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _{RM}	20	V
RMS Reverse Voltage	$V_{R(RMS)}$	14	V
Average Rectified Output Current (See Figure 1)	l ₀	3.0	Α
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	66	А

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Maximum Thermal Resistance Thermal Resistance Junction to Soldering (Note 5) Thermal Resistance Junction to Ambient (Note 6) Thermal Resistance Junction to Ambient (Note 7)	R ₀ Js R ₀ JA R ₀ JA	44 127 97	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics @T_A = +25°C unless otherwise specified

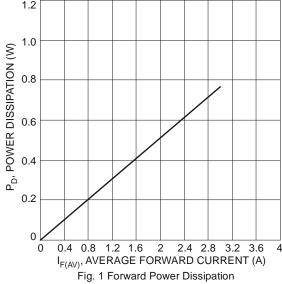
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 8)	$V_{(BR)R}$	20	-	-	V	$I_R = 0.75 \text{mA}$
Forward Voltage Drop	VF	- - - -	0.26 0.29 0.35 0.28	0.30 0.33 0.39 0.32	V	I _F = 0.5A, T _J = +25°C I _F = 1.0A, T _J = +25°C I _F = 3.0A, T _J = +25°C I _F = 3.0A, T _J = +125°C
Leakage Current (Note 8)	I _R	-	-	500 100	μA mA	$V_R = 20V, T_J = +25$ °C $V_R = 20V, T_J = +125$ °C

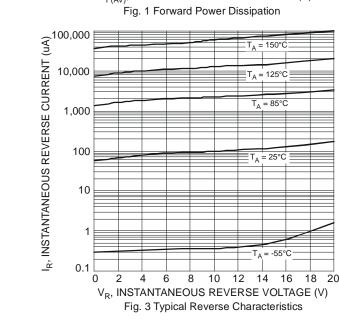
Notes:

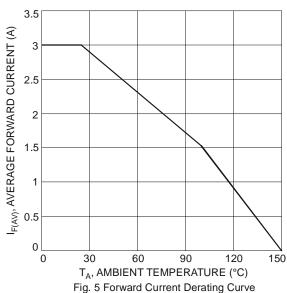
- 5. Theoretical R_{0JS} calculated from the top center of the die straight down to the PCB cathode tab solder junction.
- 6. FR-4 PCB, 2 oz. Copper, minimum recommended pad layout per http://www.diodes.com/datasheets/ap02001.pdf, T_A = +25°C.
- 7. Polymide PCB, 2 oz. Copper, minimum recommended pad layout per http://www.diodes.com/datasheets/ap02001.pdf.
- 8. Short duration pulse test used to minimize self-heating effect.

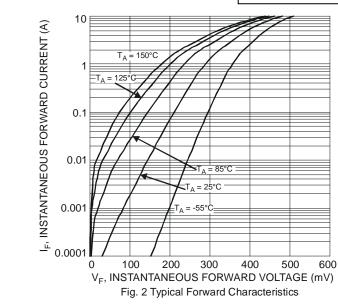


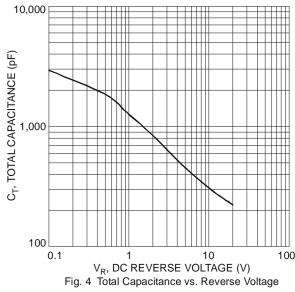


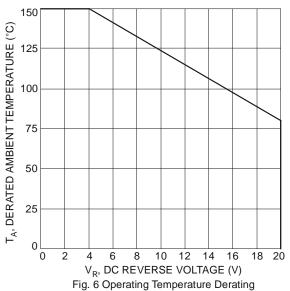








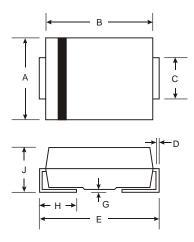






Package Outline Dimensions

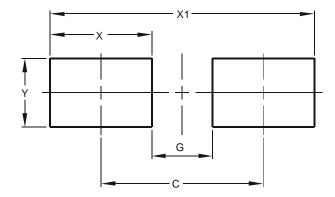
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SMA			
Dim	Min	Max	
Α	2.29	2.92	
В	4.00	4.60	
С	1.27	1.63	
D	0.15	0.31	
Е	4.80	5.59	
G	0.05	0.20	
Н	0.76	1.52	
J	2.01	2.30	
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for latest version.



Dimensions	Value (in mm)
С	4.00
G	1.50
Х	2.50
X1	6.50
Y	1.70



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